



ALPHA & OMEGA
SEMICONDUCTOR

AOTF7T60

600V,7A N-Channel MOSFET

General Description

- Latest Trench Power AlphaMOS-II technology
- Low $R_{DS(ON)}$
- Low Ciss and Crss
- High Current Capability
- RoHS and Halogen Free Compliant

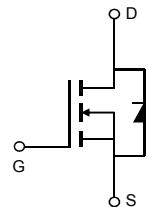
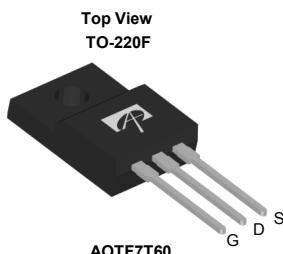
Applications

- General Lighting for LED and CCFL
- AC/DC Power supplies for Industrial, Consumer, and Telecom

Product Summary

V_{DS} @ $T_{j,max}$	700V
I_{DM}	28A
$R_{DS(ON),max}$	< 1.1Ω
$Q_{g,typ}$	16nC
E_{oss} @ 400V	2.5μJ

100% UIS Tested
100% R_g Tested



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOTF7T60	TO-220F Pb Free	Tube	1000
AOTF7T60L	TO-220F Green	Tube	1000

Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	AOTF7T60	AOTF7T60L	Units
Drain-Source Voltage	V_{DS}	600		V
Gate-Source Voltage	V_{GS}		±30	V
Continuous Drain Current	I_D	7*	7*	A
$T_C=100^\circ\text{C}$		5*	5*	
Pulsed Drain Current ^C	I_{DM}	28		
Avalanche Current ^{C,J}	I_{AR}	7		A
Repetitive avalanche energy ^{C,J}	E_{AR}	25		mJ
Single pulsed avalanche energy ^G	E_{AS}	270		mJ
MOSFET dv/dt ruggedness	dv/dt	50		V/ns
Peak diode recovery dv/dt		5		
Power Dissipation ^B	P_D	38	29	W
$T_C=25^\circ\text{C}$		0.3	0.2	W/°C
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150		°C
Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	T_L	300		°C
Thermal Characteristics				
Parameter	Symbol	AOTF7T60	AOTF7T60L	Units
Maximum Junction-to-Ambient ^{A,D}	$R_{\theta JA}$	65	65	°C/W
Maximum Junction-to-Case	$R_{\theta JC}$	3.3	4.3	°C/W

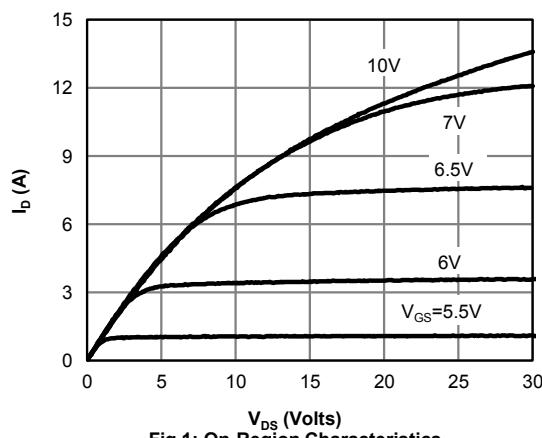
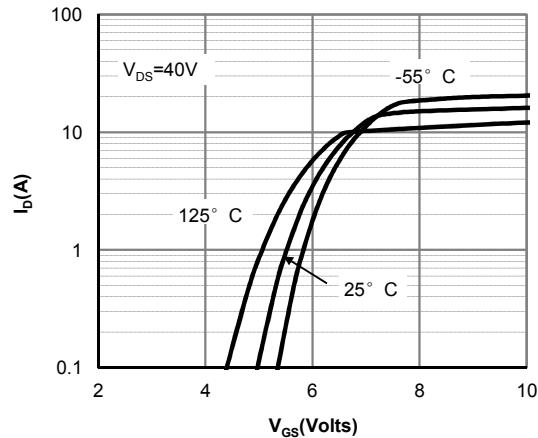
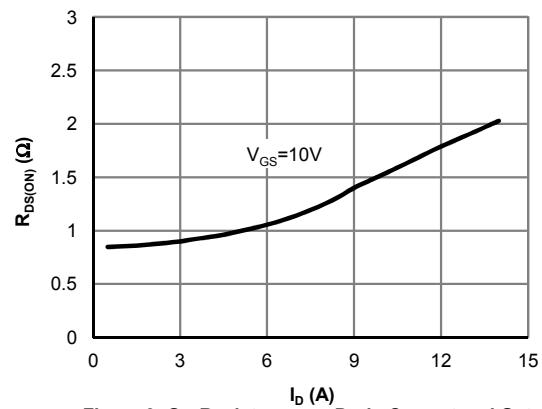
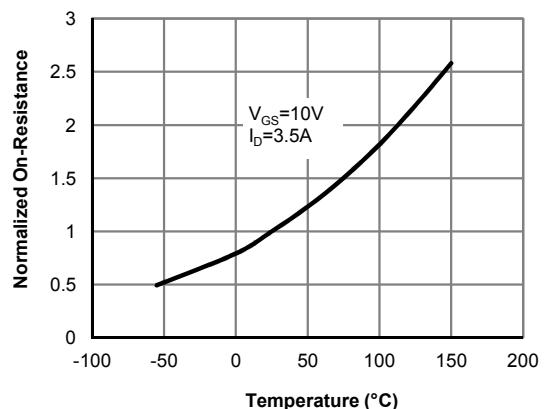
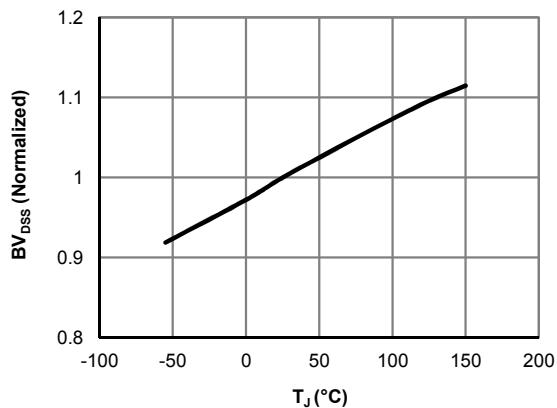
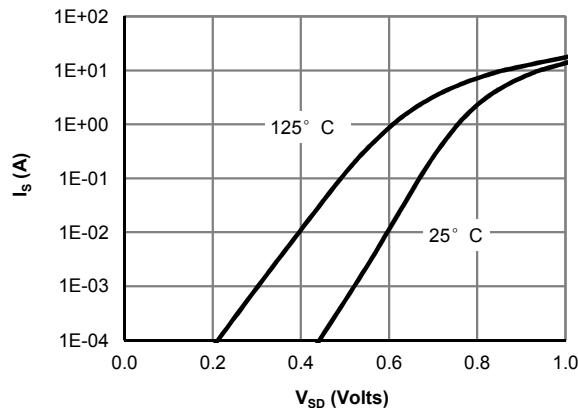
* Drain current limited by maximum junction temperature.

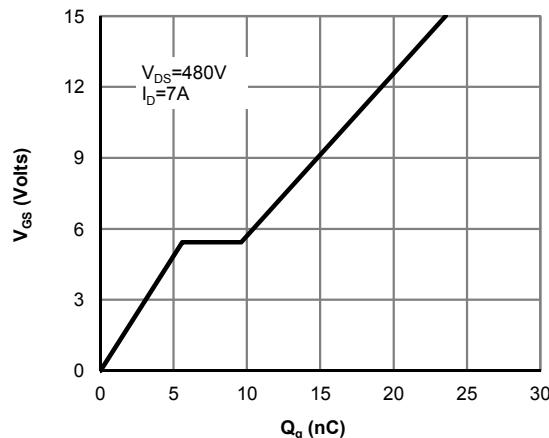
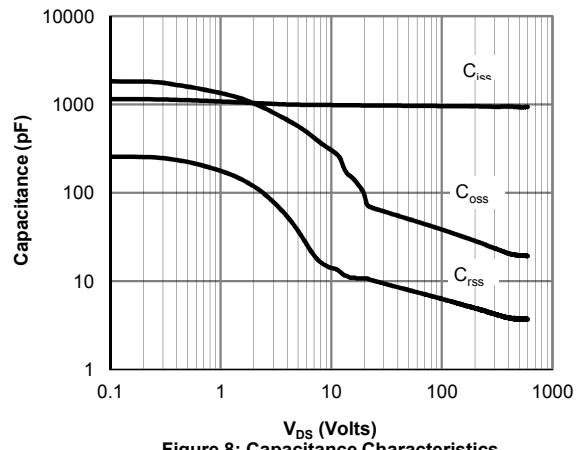
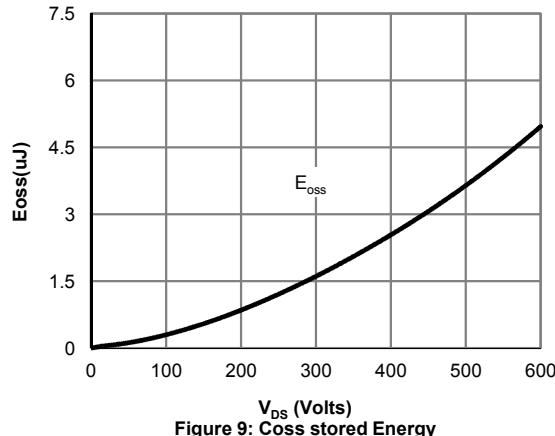
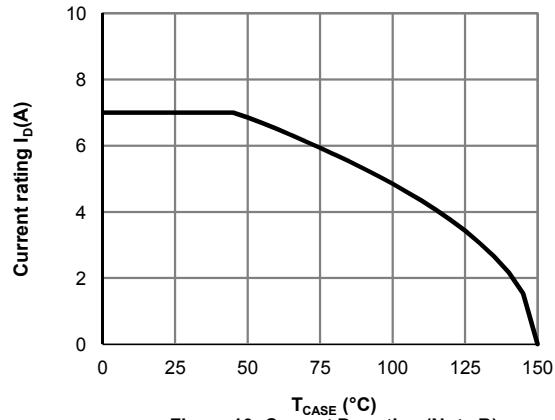
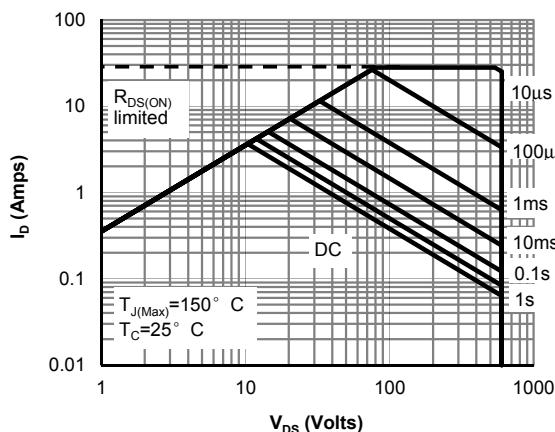
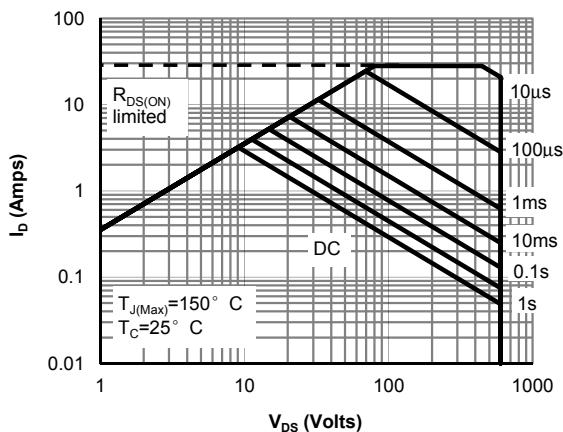
Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V, T _J =25°C	600			V
		I _D =250μA, V _{GS} =0V, T _J =150°C		700		
BV _{DSS} /ΔT _J	Breakdown Voltage Temperature Coefficient	I _D =250μA, V _{GS} =0V		0.58		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =600V, V _{GS} =0V			1	μA
		V _{DS} =480V, T _J =125°C			10	
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±30V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =5V, I _D =250μA	3	4	5	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =3.5A		0.92	1.1	Ω
g _{FS}	Forward Transconductance	V _{DS} =40V, I _D =3.5A		6.3		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.77	1	V
I _S	Maximum Body-Diode Continuous Current				7	A
I _{SM}	Maximum Body-Diode Pulsed Current ^C				28	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =100V, f=1MHz		962		pF
C _{oss}	Output Capacitance			38		pF
C _{o(er)}	Effective output capacitance, energy related ^H	V _{GS} =0V, V _{DS} =0 to 480V, f=1MHz		30		pF
C _{o(tr)}	Effective output capacitance, time related ^I			51		pF
C _{rss}	Reverse Transfer Capacitance	V _{GS} =0V, V _{DS} =100V, f=1MHz		6.3		pF
R _g	Gate resistance	f=1MHz		3.7		Ω
SWITCHING PARAMETERS						
Q _g	Total Gate Charge	V _{GS} =10V, V _{DS} =480V, I _D =7A		16	24	nC
Q _{gs}	Gate Source Charge			5.6		nC
Q _{gd}	Gate Drain Charge			4		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =300V, I _D =7A, R _G =25Ω		27		ns
t _r	Turn-On Rise Time			40		ns
t _{D(off)}	Turn-Off DelayTime			38		ns
t _f	Turn-Off Fall Time			27		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =7A, dI/dt=100A/μs, V _{DS} =100V		426		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =7A, dI/dt=100A/μs, V _{DS} =100V		5		μC

- A. The value of R_{θJA} is measured with the device in a still air environment with T_A=25°C.
B. The power dissipation P_D is based on T_{J(MAX)}=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
C. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C. Ratings are based on low frequency and duty cycles to keep initial T_J=25°C.
D. The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.
E. The static characteristics in Figures 1 to 6 are obtained using <300 μs pulses, duty cycle 0.5% max.
F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=150°C. The SOA curve provides a single pulse rating.
G. L=60mH, I_{AS}=3A, V_{DD}=150V, R_G=25Ω, Starting T_J=25°C.
H. C_{o(er)} is a fixed capacitance that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{(BR)DSS}.
I. C_{o(tr)} is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{(BR)DSS}.
J. L=1.0mH, V_{DD}=150V, R_G=25Ω, Starting T_J=25°C.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Fig 1: On-Region Characteristics

Figure 2: Transfer Characteristics

Figure 3: On-Resistance vs. Drain Current and Gate Voltage

Figure 4: On-Resistance vs. Junction Temperature

Figure 5: Break Down vs. Junction Temperature

Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

Figure 9: Coss stored Energy

Figure 10: Current De-rating (Note B)

Figure 11: Maximum Forward Biased Safe Operating Area for AOTF7T60 (Note F)

Figure 12: Maximum Forward Biased Safe Operating Area for AOTF7T60L (Note F)

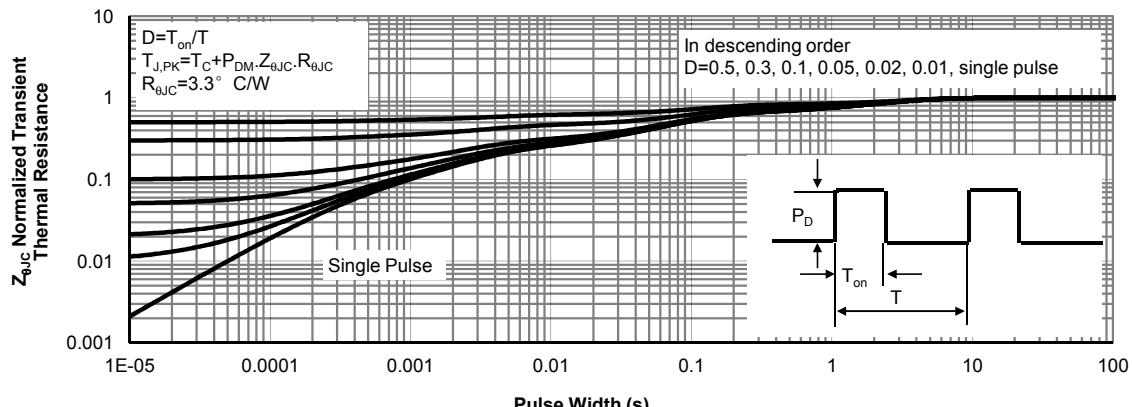
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS


Figure 13: Normalized Maximum Transient Thermal Impedance for AOTF7T60 (Note F)

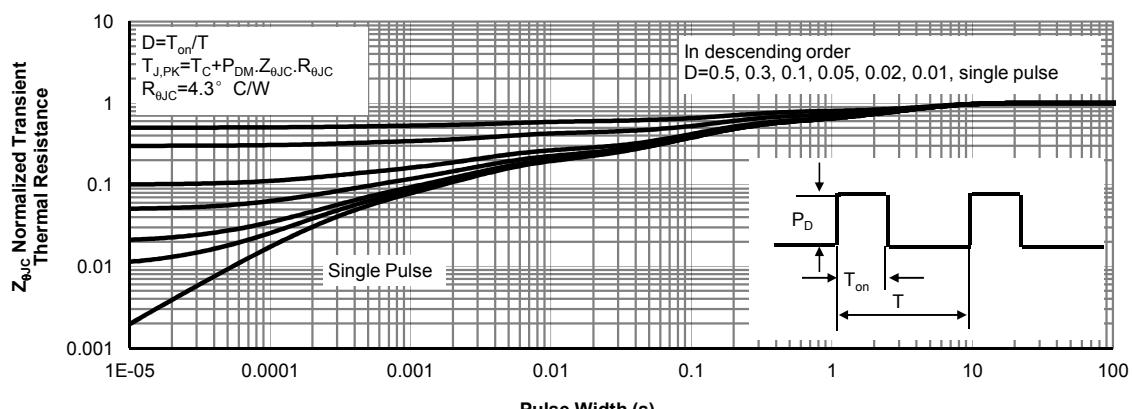
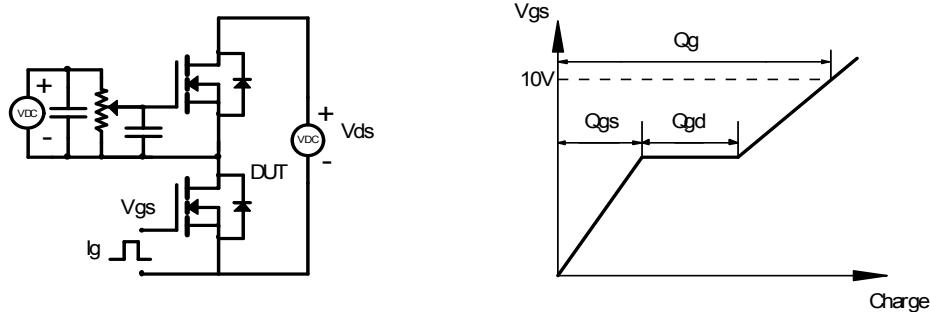
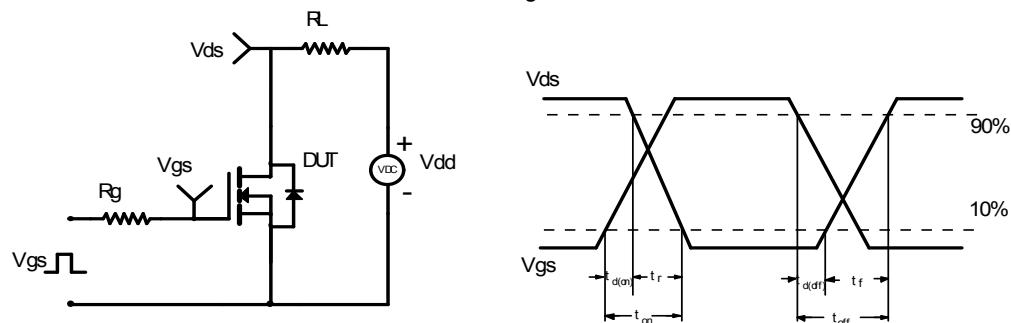
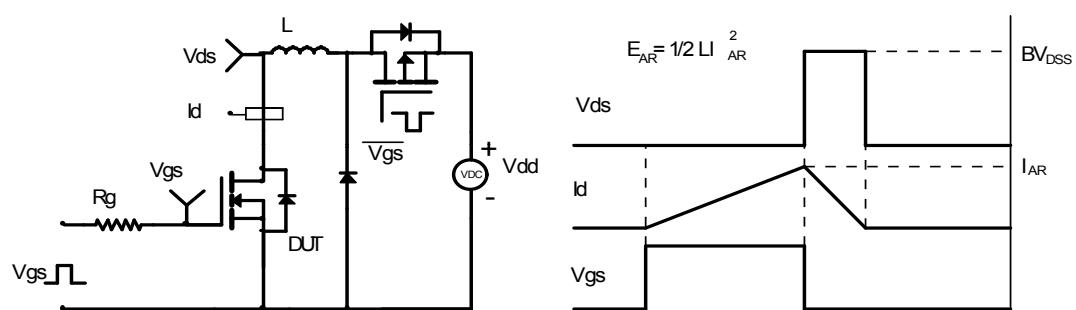


Figure 14: Normalized Maximum Transient Thermal Impedance for AOTF7T60L (Note F)

Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

Diode Recovery Test Circuit & Waveforms
